

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
HOLGER SPECHT	02/27/2019
ROLAND ZEISEL	02/27/2019
ANTON VOGL	02/27/2019
JENS EBBECKE	02/28/2019
<b>RECEIVING PARTY DATA</b>	
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<b>Street Address:</b>	Leibnizstrasse 4
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<b>Postal Code:</b>	93055
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	16323237
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<b>ATTORNEY DOCKET NUMBER:</b>	OSR-562-EH
<b>NAME OF SUBMITTER:</b>	JENNIFER PILCHER
<b>SIGNATURE:</b>	/Jennifer Pilcher/
<b>DATE SIGNED:</b>	03/20/2019
<b>Total Attachments: 2</b>	
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**ASSIGNMENT**

For good and valuable consideration, I, Holger Specht, residing at Erich-Ollenhauer-Str. 25, 93077 Bad Abbach, Germany, a citizen of Germany; Roland Zeisel, residing at Klöpfelweg 6, 93105 Tegernheim, Germany, a citizen of Germany; Anton Vogl, residing at Waldstr.7, 93161 Sinzing, Germany, a citizen of Germany; Jens Ebbecke, residing at Am Doppelfeld 7, 93352 Rohr in Niederbayern, Germany, a citizen of Germany;

hereby sell, assign, and transfer to OSRAM Opto Semiconductors GmbH, a corporation organized and existing under the laws of Germany, having its principal place of business at Leibnizstrasse 4, 93055 Regensburg, Germany;

hereinafter "Assignee," its successors, assigns and legal representatives, the entire right, title and interest in and for the United States and all foreign countries, in and to any and all improvements which are disclosed in U.S. Patent Application No. 16/323,237 filed 2/4/2019, which is entitled "Method and Device for Measurement of a Plurality of Semiconductor Chips in a Wafer Array," and in and to said application and all divisional, continuing substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said improvements;

Agree that Assignee may apply for and receive Letters Patent for said improvements in its own name, and that, when requested, without charge to but at the expense of said Assignee, their successors, assigns, and legal representatives to carry out in good faith the intent and purpose of this agreement, the undersigned will execute all divisional, continuing substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns, or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Date: February 27. 2019

Holger Specht  
Holger Specht

Date: February 27. 2019

Roland Zeise  
Roland Zeise

Date: February 27. 2019

Anton Vogl  
Anton Vogl

Date: February 28. 2019

Jens Ebbecke  
Jens Ebbecke